



# SOD1608

DFN1608D-2: leadless ultra small plastic package; 2 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN1608D-2
<b>Package type industry code</b>	DFN1608D-2
<b>Package style descriptive code</b>	SOD (small outline diode)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	29-11-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.75	-	0.8	0.85	mm
E	package width	1.55	-	1.6	1.65	mm
A	seated height	0.34	-	0.37	0.4	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

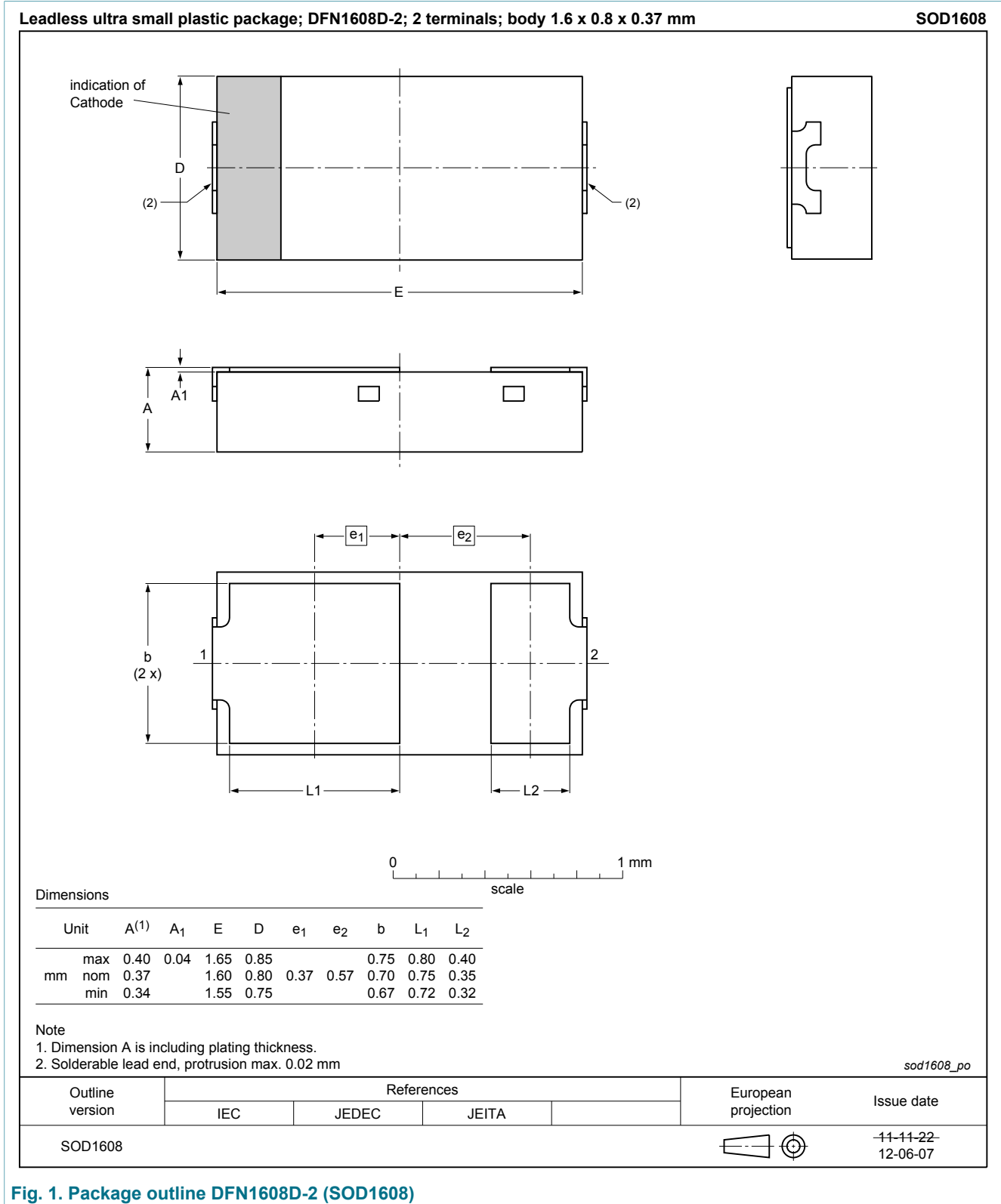


Fig. 1. Package outline DFN1608D-2 (SOD1608)

### 3. Soldering

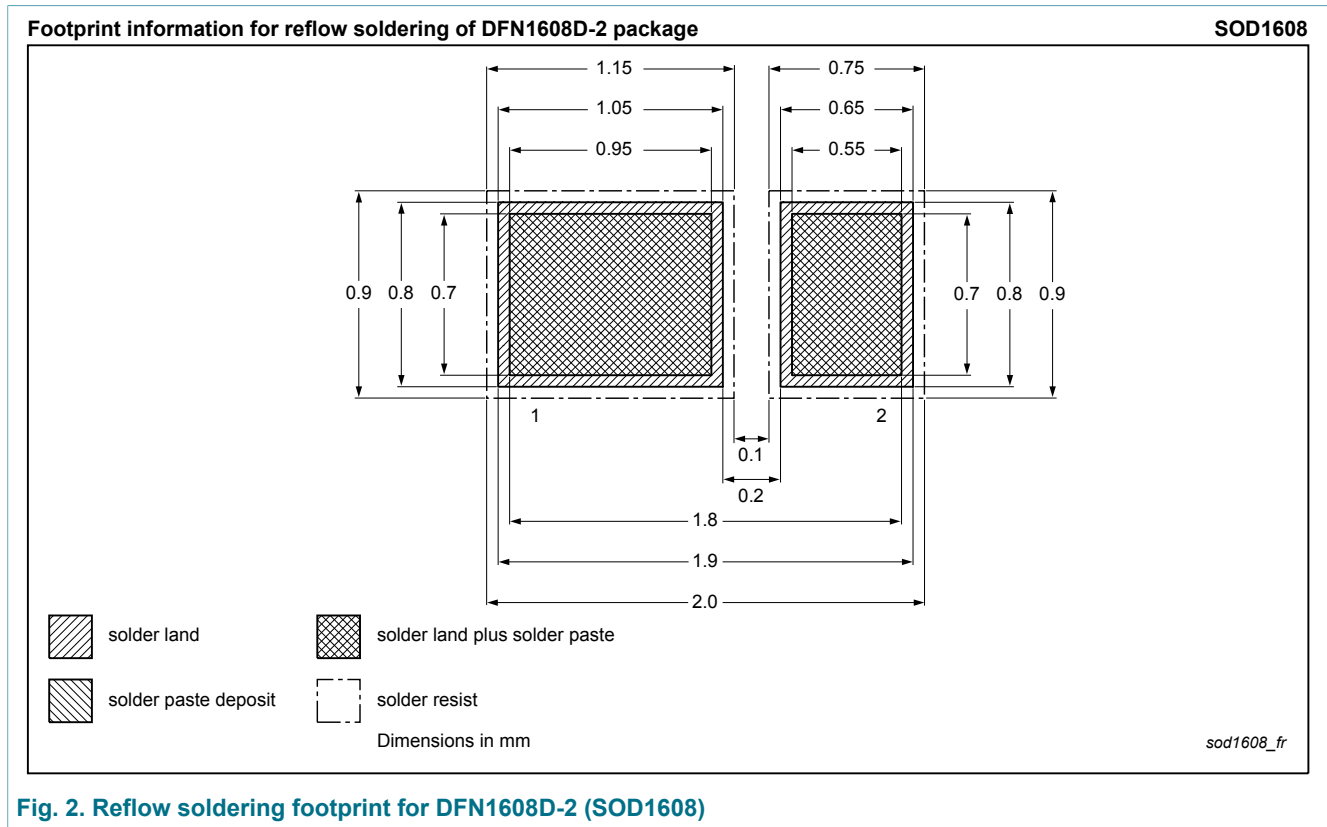


Fig. 2. Reflow soldering footprint for DFN1608D-2 (SOD1608)

## 4. Legal information

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Date of release: 8 February 2016

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